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Read Statement

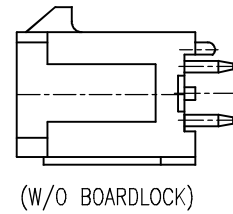
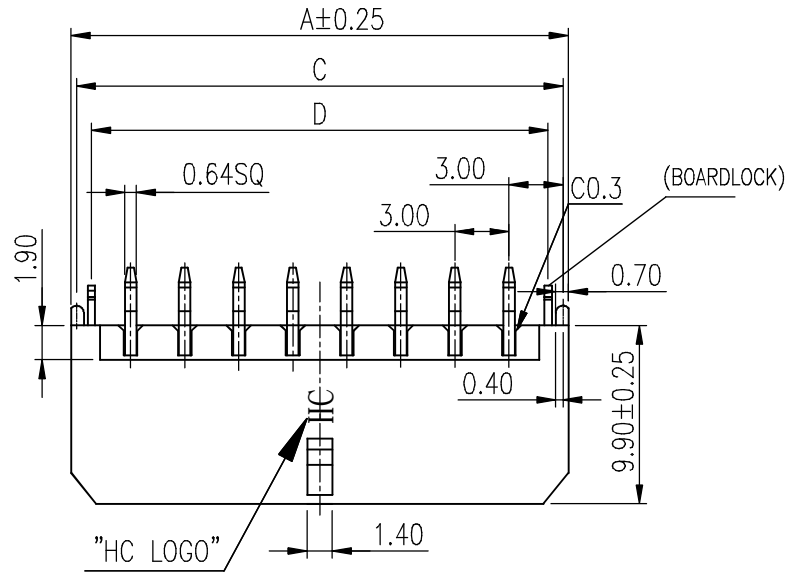
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The marking on this product doesn't contain environmental hazardous materials per Material Specification SS-00259 for Sony GP compliant or per directive 2011/65/EU for RoHS compliant.

FOR REFERENCE ONLY

REVISIONS				
SYM	ECN No.	DESCRIPTION	DATE	APPROVED
A	NE-14098	RELEASE FOR RoHS	06/14/2014	Arron Lin
BX1	EDSR#5399	ADD W/O BOARDLOCK OPTION	02/10/2015	Arron Lin



NOTE:

1.MATERIAL

INSULATOR: HIGH TEMP. THERMOPLASTIC, OPTIONS, UL 94V-0, COLOR OPTIONS
 CONTACT MATERIAL: HIGH PERFORMANCE COPPER ALLOY.
 BOARDLOCK: COPPER ALLOY.

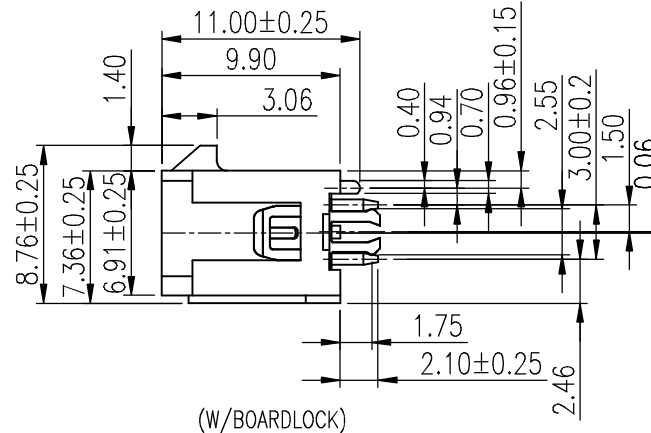
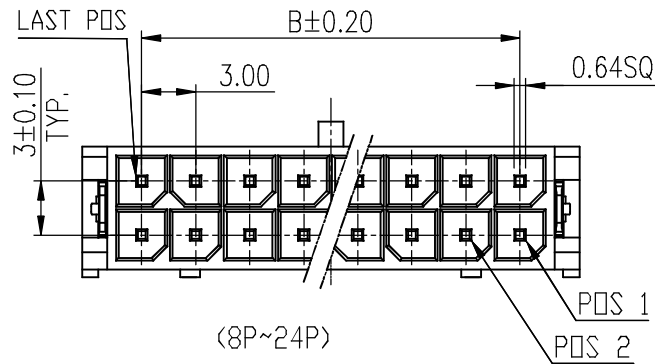
2.FINISH:

CONTACT: SELECTIVE PLATING. ;
 SOLDERING AREA: MATTE TIN 100u" MIN. OR GOLD PLATING;
 UNDER PLATING: NICKEL PLATING 50 μ" THICKNESS MIN.OVERALL.
 BOARDLOCK:
 MATTE TIN 100u" MIN. PLATING;
 UNDER PLATING: NICKEL PLATING 50 μ" THICKNESS MIN.OVERALL.

4.THIS PRODUCT DOESN'T ENVIRONMENTAL HAZARDOUS MATERIALS PER DIRECTIVE 2011/65/EU FOR RoHS.

5.PACKING MUST BE PER Amphenol PACKING SPECIFICATION

6.TO ENSURE CURRENT RATING CAPABILITY, PLEASE ADOPT TOTAL SOLUTION. (G88MPH CABLE HOUSING SERIES WITH G88MPC CABLE TERMINAL SERIES)



POS	A	B	C	D
02	6.60		6.00	4.3
04	9.60	3.00	9.00	7.3
06	12.60	6.00	12.00	10.3
08	15.60	9.00	15.00	13.3
10	18.60	12.00	18.00	16.3
12	21.60	15.00	21.00	19.3
14	24.60	18.00	24.00	22.3
16	27.60	21.00	27.00	25.3
18	30.60	24.00	30.00	28.3
20	33.60	27.00	33.00	31.3
22	36.60	30.00	36.00	34.3
24	39.60	33.00	39.00	37.3

PART NO. G88MPXX1X2XXEU

No. OF CIRCUIT ——— BOARD MOUNT OPTION
 C: W/BOARDLOCK
 D: W/O BOARDLOCK

CONTACT FINISH ——— INSULATOR
 0: MATTE TIN (OVERALL) ——— BLANK: LCP (BLACK)
 UNDER PLATING NICKEL 50 μ" THICKNESS MIN ——— 1: LCP (NATURAL)
 1: FLASH GOLD (OVERALL)
 2: 15 u" GOLD
 3: 30 u" GOLD

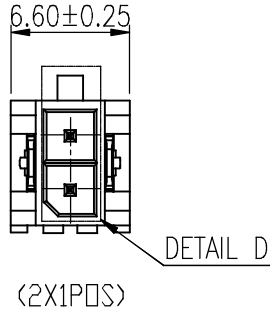
TOLERANCE	APPROVALS	DATE	TITLE		Amphenol® Amphenol Corporation Amphenol Taiwan Corporation			
X. ±0.30	DRAWN Debby Hung	02/10/2015	G88MP SERIES MICRO POWER PLUS, WAFER 3.00 MM PITCH STRAIGHT DIP, W/BLOCK		UNIT mm	SIZE A3	PART No. G88MPXX1X2XXEU	
X.X ±0.20							CHECKED Roger Tsai	02/10/2015
X.XXX ±0.10	APPROVED Arron Lin	02/10/2015	PROJECT CODE PHD					
ANGULAR ±1°	DWG TYPE CUST DWG	UNLESS OTHERWISE SPECIFIED						

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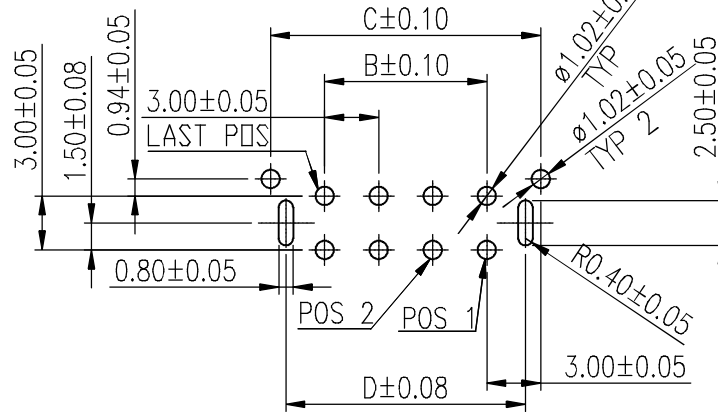
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BX1	EDSR#5399	ADD W/O BOARDLOCK OPTION	02/10/2015	Arron Lin

FOR REFERENCE ONLY

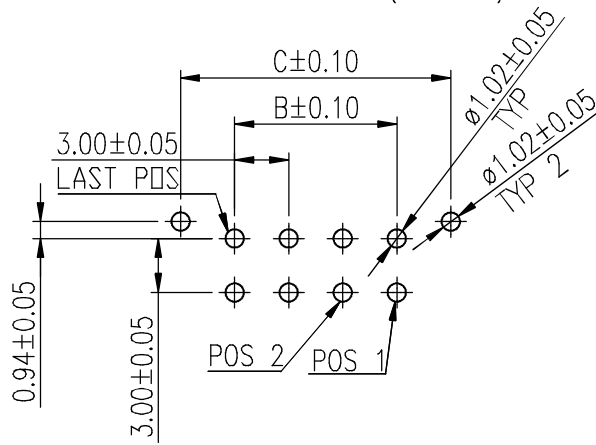
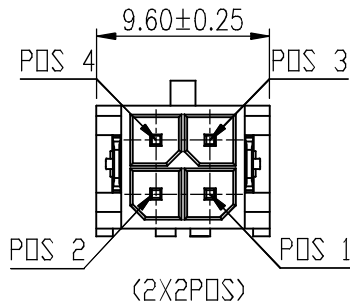


DETAIL D



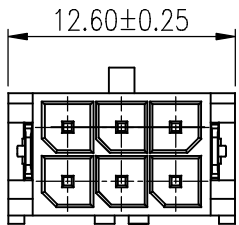
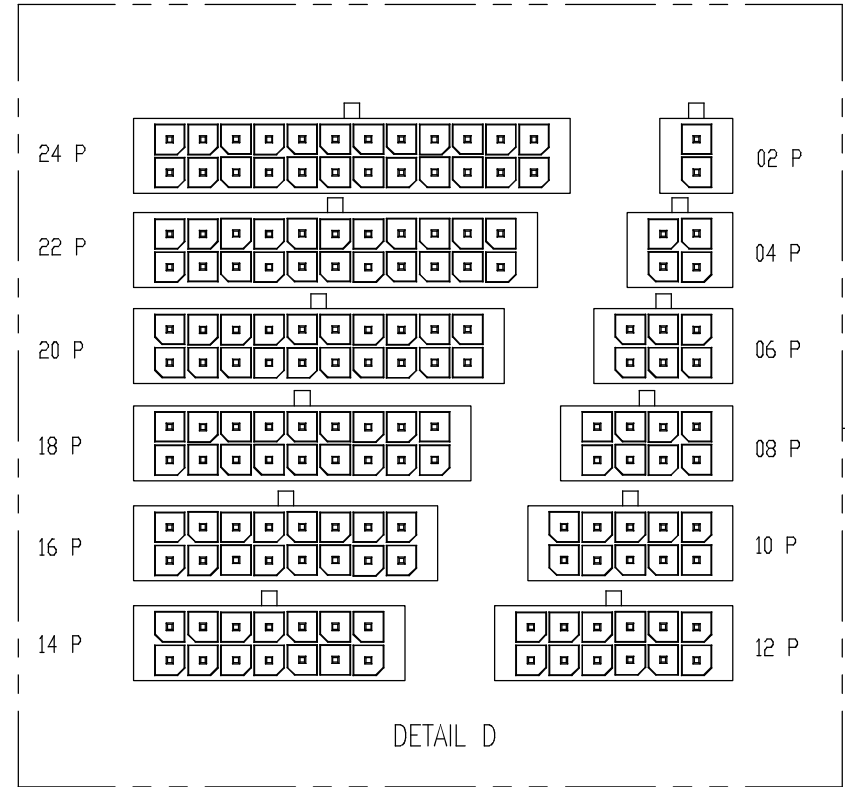
02~24P (W/BOARDLOCK)

RECOMMENDED PCB LAYOUT (T=1.60mm)



02~24P (W/O BOARDLOCK)

RECOMMENDED PCB LAYOUT (T=1.60mm)



TOLERANCE	APPROVALS	DATE	TITLE		PART No.	
X. ±0.30	DRAWN Debby Hung	02/10/2015	G88MP SERIES MICRO POWER PLUS, WAFER 3.00 MM PITCH STRAIGHT DIP, W/BLOCK		Amphenol® Amphenol Corporation Amphenol Taiwan Corporation	
X.X ±0.20	CHECKED Roger Tsai	02/10/2015				
X.XXX ±0.10	APPROVED Arron Lin	02/10/2015				
ANGULAR ±1°	DWG TYPE CUST DWG	PROJECT CODE PHD	UNIT mm	SIZE A3	G88MPXX1X2XXEU	
UNLESS OTHERWISE SPECIFIED			SCALE NA	SHEET 2 OF 4	DWG No. G88MPXX1X2XXEU	REV. BX1

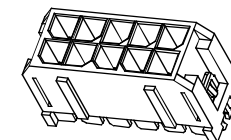
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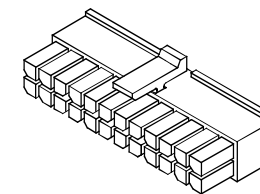
REVISIONS				
SYM	ECN No.	DESCRIPTION	DATE	APPROVED
A	NE-14098	RELEASE FOR RoHS	06/14/2014	Arron Lin
BX1	EDSR#5399	ADD W/O BOARDLOCK OPTION	02/10/2015	Arron Lin

FOR REFERENCE ONLY

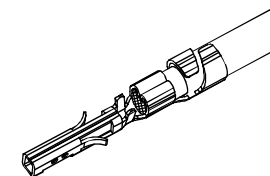
POS.	BOARD-MOUNT P/N	CABLE HOUSING P/N	CABLE TERMINAL P/N	AWG NO.	PLATING OPTIONS
02	G88MP021X2XXEU	G88MPH0222CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
04	G88MP041X2XXEU	G88MPH0422CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
06	G88MP061X2XXEU	G88MPH0622CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
08	G88MP081X2XXEU	G88MPH0822CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
10	G88MP101X2XXEU	G88MPH1022CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
12	G88MP121X2XXEU	G88MPH1222CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
14	G88MP141X2XXEU	G88MPH1422CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
16	G88MP161X2XXEU	G88MPH1622CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
18	G88MP181X2XXEU	G88MPH1822CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
20	G88MP201X2XXEU	G88MPH2022CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
22	G88MP221X2XXEU	G88MPH2222CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD
24	G88MP241X2XXEU	G88MPH2422CEU	G88MPCX232CEU	AWG#16~18	0: TIN 100u" ; 1: FLASH GOLD
			G88MPCX332CEU	AWG#20~30	2: 15u" GOLD ; 3: 30u" GOLD



AMPHENOL BOARD-MOUNT



AMPHENOL CABLE HOUSING



AMPHENOL CABLE TERMINAL

NOTE:
TO ENSURE CURRENT RATING CAPABILITY, PLEASE ADOPT TOTAL SOLUTION.
(G88MPH CABLE HOUSING SERIES WITH G88MPC CABLE TERMINAL SERIES)

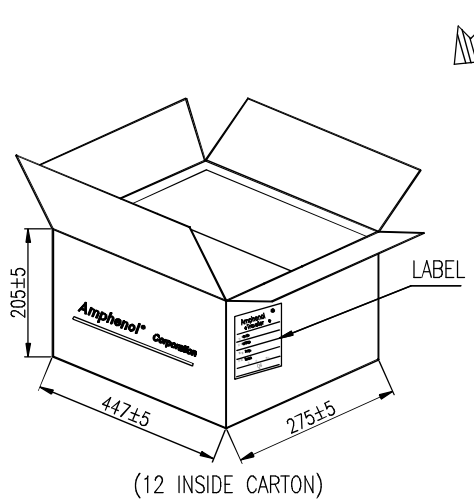
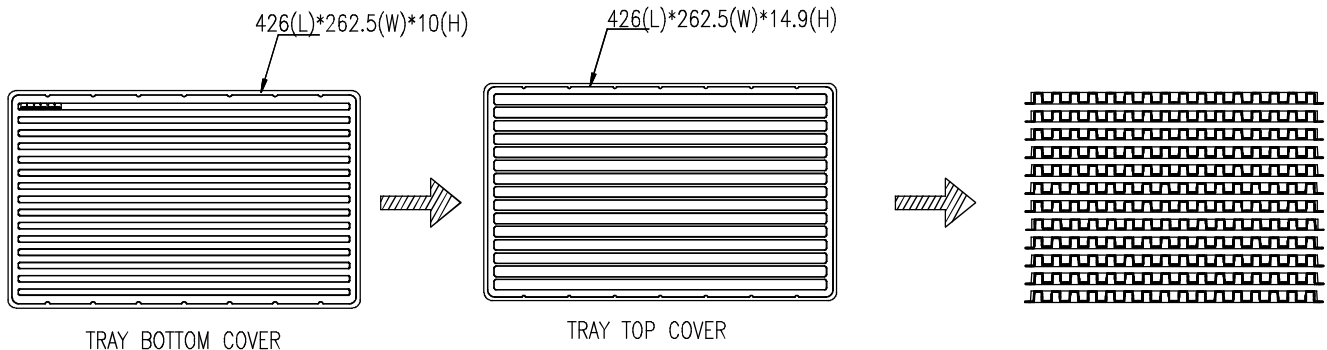
TOLERANCE	APPROVALS	DATE	TITLE		PART No.	
X. X.X ±0.30 X.XX ±0.20 X.XXX ±0.10	DRAWN Debby Hung	02/10/2015	G88MP SERIES MICRO POWER PLUS, WAFER 3.00 MM PITCH STRAIGHT DIP, W/BLOCK		Amphenol [®] Amphenol Corporation Amphenol Taiwan Corporation	
ANGULAR ±1°	CHECKED Roger Tsai	02/10/2015	UNIT mm	SIZE A3	PART No. G88MPXX1X2XXEU	
UNLESS OTHERWISE SPECIFIED	APPROVED Arron Lin	02/10/2015	SCALE NA	SHEET 3 OF 4	DWG No. G88MPXX1X2XXEU	REV. BX1
	DWG TYPE CUST DWG	PROJECT CODE PHD				

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POS	PCS/TRAY	PCS/CARTON
2	900	10800
4	615	7380
6	465	5580
8	375	4500
10	315	3780
12	270	3240
14	240	2880
16	210	2520
18	180	2160
20	165	1980
22	150	1800
24	150	1800

- NOTE:
1. MATERIAL : BLACK CONDUCTIVE POLYSTYRENE ALLOY
 2. ALL DIMENSIONS MEET EIA-481-C REQUIREMENTS.
 3. THICKNESS : 0.80±0.05mm.

TOLERANCE	APPROVALS	DATE	TITLE		Amphenol [®]	
X. ±0.30	DRAWN Debby Hung	02/10/2015	G88MP SERIES MICRO POWER PLUS, WAFER 3.00 MM PITCH STRAIGHT DIP, W/BLOCK		Amphenol Corporation	
X.X ±0.20					CHECKED Roger Tsai	02/10/2015
X.XXX ±0.10	APPROVED Arron Lin	02/10/2015	UNITS mm	SIZE A3	PART No. G88MPXX1X2XXEU	
ANGULAR ±1°	DWG TYPE CUST DWG	PROJECT CODE PHD			SCALE NA	SHEET 4 OF 4
UNLESS OTHERWISE SPECIFIED						